



Customer No.: 31561  
Application No.: 10/707,609  
Docket No.: 10073-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Examiner: Trinh, Hoa B

Group Art Unit: 2814

In re PATENT APPLICATION of

Applicants : Yu-Wen Chen

Serial No. : 10/707,609

Filed : December 24, 2003

For : Flip Chip Package Structure

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) AMENDMENT  
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) Attorney Docket: 10073-US-PA  
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**No fee is believed to be due. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10073-US-PA)**

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

U.S. Patent and Trademark Office  
Commissioner for Patents  
Customer Service Window, Mail Stop Amendment  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Dear Sir:

The Office Action dated December 09, 2004, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.